

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4649112

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|---|-------------------------------------|
| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| MASAHIRO MATSUMOTO | 06/04/2017 |
| AKIRA YAJIMA | 10/13/2017 |
| KAZUYOSHI MAEKAWA | 05/11/2017 |
| RECEIVING PARTY DATA | |
| Name: | RENESAS ELECTRONICS CORPORATION |
| Street Address: | 2-24, TOYOSU 3-CHOME, KOUTOU-KU |
| City: | TOKYO |
| State/Country: | JAPAN |
| Postal Code: | 135-0061 |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 15621745 |
| CORRESPONDENCE DATA | |
| Fax Number: | (703)761-2375 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Phone: | 7037614100 |
| Email: | admin@mcginniplaw.com |
| Correspondent Name: | MCGINN I.P. LAW GROUP, PLLC |
| Address Line 1: | 8321 OLD COURTHOUSE ROAD, SUITE 200 |
| Address Line 4: | VIENNA, VIRGINIA 22182-3817 |
| ATTORNEY DOCKET NUMBER: | TSUT.041 |
| NAME OF SUBMITTER: | SEAN M. MCGINN |
| SIGNATURE: | /SEAN M. MCGINN/ |
| DATE SIGNED: | 10/19/2017 |
| Total Attachments: 3 | |
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| source=745_Assignment#page2.tif | |
| source=745_Assignment#page3.tif | |

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 2-24, Toyosu 3-chome, Koutou-ku, Tokyo 135-0061, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Masahiro Matsumoto (Masahiro MATSUMOTO)

June 4, 2017

2) _____ (Akira YAJIMA)

3) _____ (Kazuyoshi MAEKAWA)

4) _____

5) _____

6) _____

PATENT

REEL: 043906 FRAME: 0585

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And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

| INVENTOR(S) (発明者フルネームサイン) | Date Signed (署名日) |
|---|-------------------------|
| 1) _____ (Masahiro MATSUMOTO) | _____ |
| 2) <u>Akira Yajima</u> _____ (Akira YAJIMA) | <u>October 13, 2017</u> |
| 3) _____ (Kazuyoshi MAEKAWA) | _____ |
| 4) _____ | _____ |
| 5) _____ | _____ |
| 6) _____ | _____ |

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to be held and enjoyed by said Renesas Electronics Corporation,

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And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

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|---|----------------------|
| 1) _____ (Masahiro MATSUMOTO) | _____ |
| 2) _____ (Akira YAJIMA) | _____ |
| 3) <u>Kazuyoshi Maekawa</u> (Kazuyoshi MAEKAWA) | <u>May 11, 2017</u> |
| 4) _____ | _____ |
| 5) _____ | _____ |
| 6) _____ | _____ |